

SN74ALVCH16344

1-TO-4 ADDRESS DRIVER WITH 3-STATE OUTPUTS

SCES054A – SEPTEMBER 1995 – REVISED JULY 1996

- Member of the Texas Instruments *Widebus*™ Family
- *EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

The SN74ALVCH16344 is a 1-bit to 4-bit address driver used in applications where four separate memory locations must be addressed by a single address.

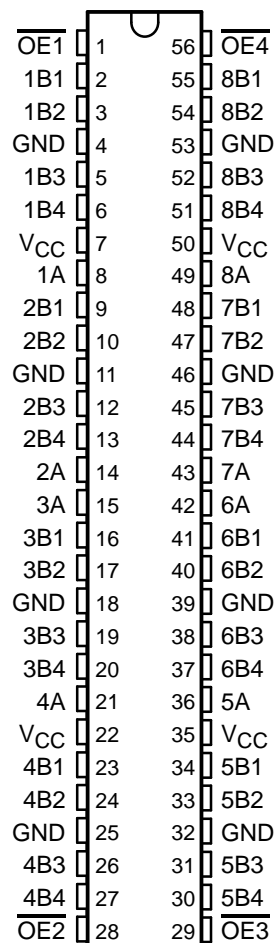
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating inputs at a valid logic level.

The SN74ALVCH16344 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVCH16344 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUTS		OUTPUT BN
\overline{OE}	A	
L	H	H
L	L	L
H	H	Z



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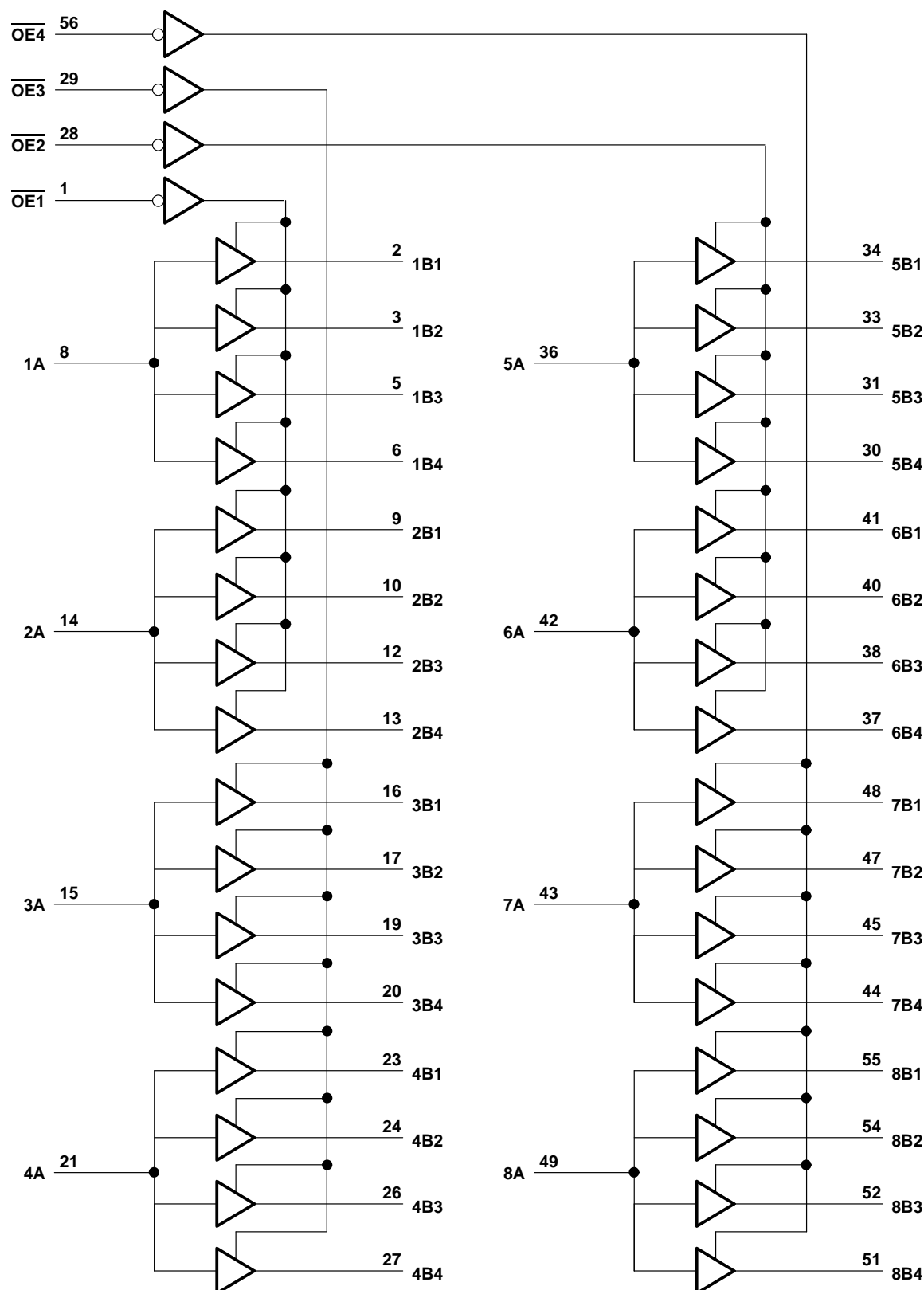
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I : Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V	0.7		V
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2.3 V	−12		mA
		V _{CC} = 2.7 V	−12		
		V _{CC} = 3 V	−24		
I _{OL}	Low-level output current	V _{CC} = 2.3 V	12		mA
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		
Δt/Δv	Input transition rise or fall rate		0	10	ns/V
T _A	Operating free-air temperature		−40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC} [†]	MIN	TYP [‡]	MAX	UNIT
V _{OH}	I _{OH} = −100 μA		MIN to MAX	V _{CC} −0.2			V
	I _{OH} = −6 mA, V _{IH} = 1.7 V		2.3 V	2			
	I _{OH} = −12 mA	V _{IH} = 1.7 V	2.3 V	1.7			
		V _{IH} = 2 V	2.7 V	2.2			
		V _{IH} = 2 V	3 V	2.4			
	I _{OH} = −24 mA, V _{IH} = 2 V		3 V	2			
V _{OL}	I _{OL} = 100 μA		MIN to MAX			0.2	V
	I _{OL} = 6 mA, V _{IL} = 0.7 V		2.3 V			0.4	
	I _{OL} = 12 mA	V _{IL} = 0.7 V	2.3 V			0.7	
		V _{IL} = 0.8 V	2.7 V			0.4	
	I _{OL} = 24 mA, V _{IL} = 0.8 V		3 V			0.55	
I _I	V _I = V _{CC} or GND		3.6 V			±5	μA
I _I (hold)	V _I = 0.7 V		2.3 V	45			μA
	V _I = 1.7 V			−45			
	V _I = 0.8 V		3 V	75			
	V _I = 2 V			−75			
	V _I = 0 to 3.6 V [§]		3.6 V			±500	
I _{OZ}	V _O = V _{CC} or GND		3.6 V			±10	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0		3.6 V			40	μA
ΔI _{CC}		One input at V _{CC} − 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	2.5			pF
	Data inputs			3.5			
C _O	Outputs	V _I = V _{CC} or GND	3.3 V	4			pF

† For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

‡ All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ This is the bus-hold maximum dynamic current required to switch the input from one state to another.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	B	1.3	5.2	4.6		1.4	4	ns
t_{en}	\overline{OE}	B	1.1	6.7	6.2		1.2	5.1	ns
t_{dis}	\overline{OE}	B	1.5	5.3	4.4		1.2	4	ns
$t_{sk(o)}^{\dagger}$							0.35		ns
$t_{sk(o)}^{\ddagger}$							0.8		ns

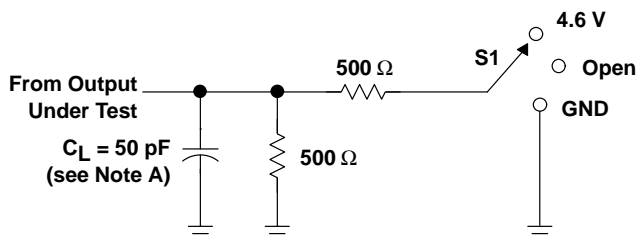
\dagger Skew between outputs of same bank and same package (same transition). This parameter is warranted but not production tested.

\ddagger Skew between outputs of all banks and same package (A1 through A8 tied together). This parameter is warranted but not production tested.

operating characteristics, $T_A = 25^\circ\text{C}$

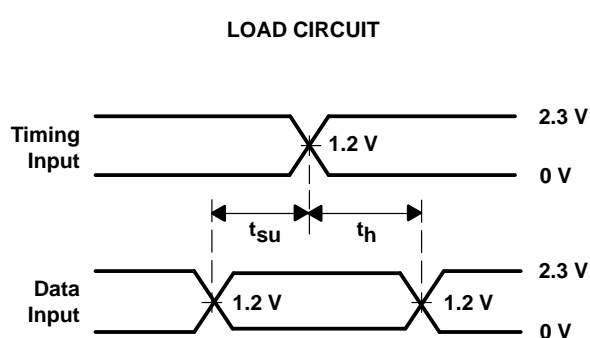
PARAMETER			TEST CONDITIONS		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$	UNIT
					TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	$C_L = 50\text{ pF}$	$f = 10\text{ MHz}$	68	84	pF
		Outputs disabled			11	14	

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

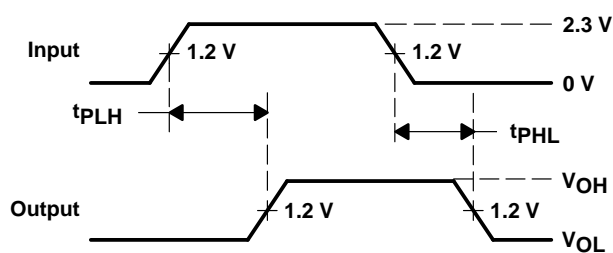


LOAD CIRCUIT

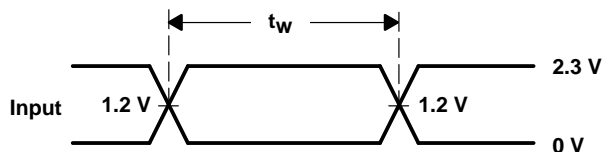
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	4.6 V
t_{PHZ}/t_{PZH}	GND



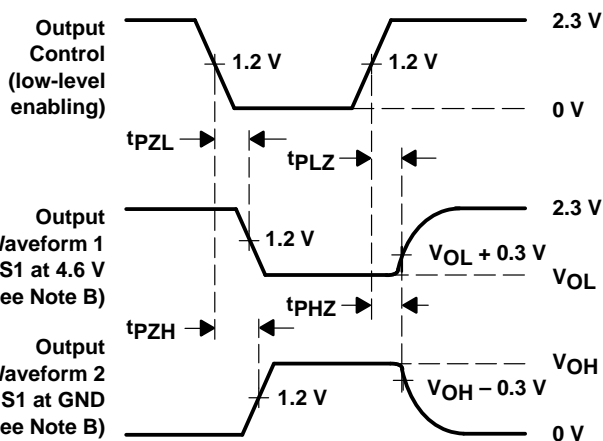
**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS
PULSE DURATION**

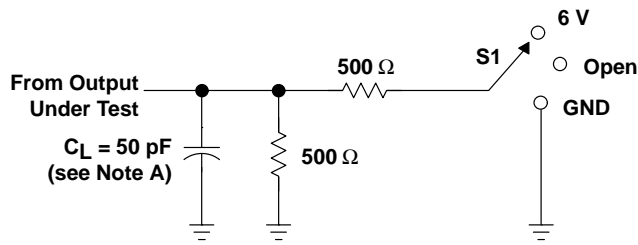


**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES**

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PHL} and t_{PLH} are the same as t_{pd} .

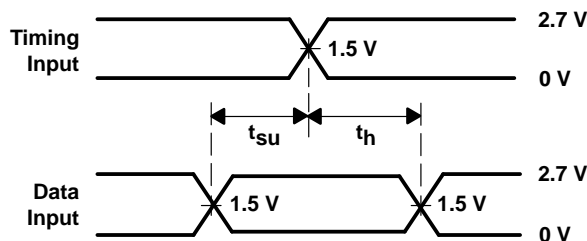
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.7\text{ V}$ AND $3.3\text{ V} \pm 0.3\text{ V}$

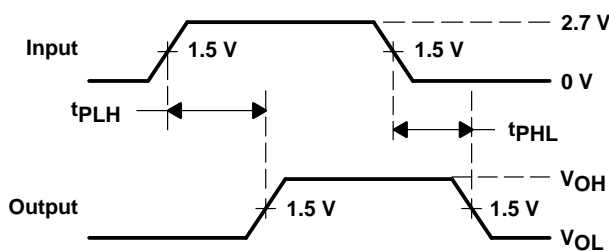


LOAD CIRCUIT

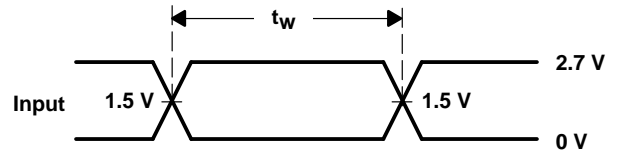
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



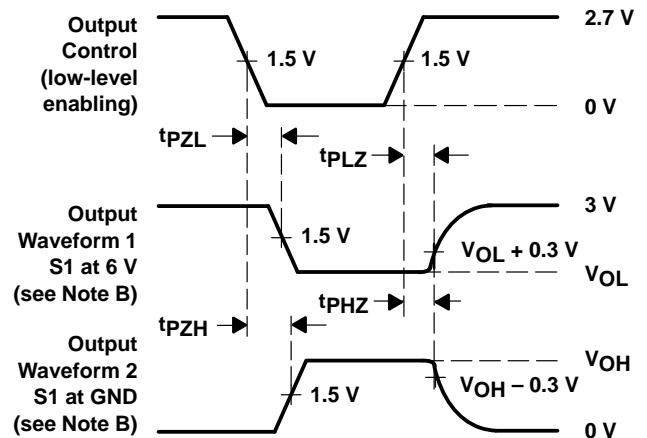
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
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D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PHL} and t_{PLH} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

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